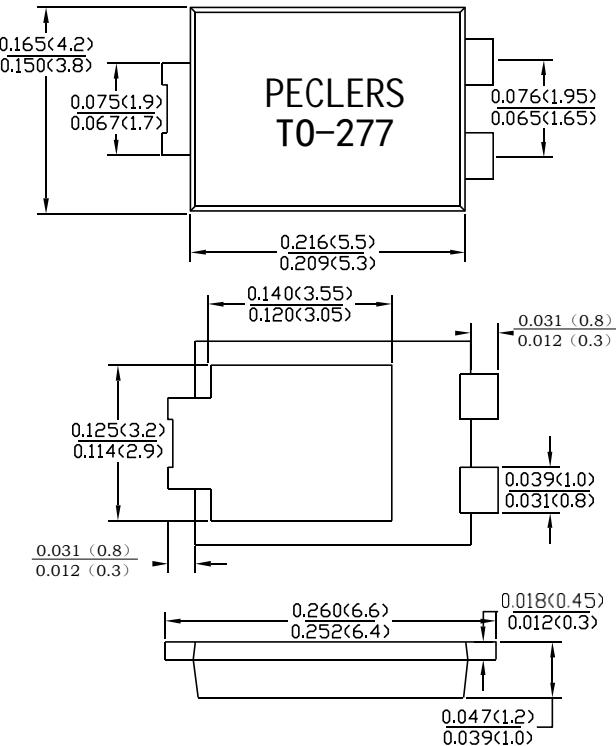


Features

- Schottky Barrier Chip
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Low Power Loss, High Efficiency
- Excellent High Temperature Stability
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case: TO-277, molded plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS/Lead Free Version



Dimensions inches and (millimeters)

Maximum Ratings and Electrical Characteristics @T_A=25 °C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbol	10V45	10V50	10V60	10V80	10V100	10V150	Unit
Peak Repetitive Reverse Voltage	V _{RRM}							
Working Peak Reverse Voltage	V _{RWM}	45	50	60	80	100	150	V
DC blocking voltage	V _{DC}							
RMS Rectified Voltage	V _{R(RMS)}	28	35	42	56	70	105	V
Average Rectified Output Current (Note1)	I _O				10			A
Non-Repetitive Peak Forward Surge 8.3ms								
Single Half Sine-Wave Superimposed on rated load (JEDEC Method) (Note2)	I _{FSM}				275			A
Forward Voltage Drop T _A =25°C @ IF=10A	V _{FM}	0.45	0.48	0.55	0.75	0.80		V
Peak Reverse Current T _A =25°C At Rated DC Blocking Voltage T _A =100°C	I _R			0.3	15			mA
Typical Thermal Resistance Junction to Ambient	R _{θJA}			80				°C/W
	R _{θJL}			15				
Operating junction temperature range	T _J			-55 to +150				°C
storage temperature range	T _{STG}			-55 to +150				°C

Note: 1. Valid provided that are kept at ambient temperature at a distance of 9.5mm from the case.

2. Fr-4pcb.2oz.Copper, minimum recommend pad layout .18.8mm×14.4mm. Anode pad dimensions 5.6mm×14.4mm.

Fig.1 - Forward Current Derating Curve

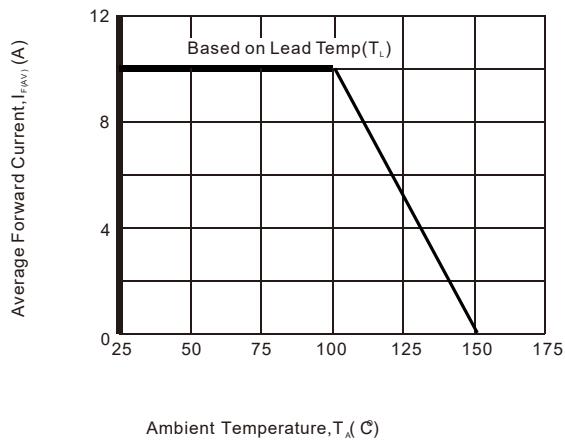


Fig2 : Instantaneous Forward Voltage

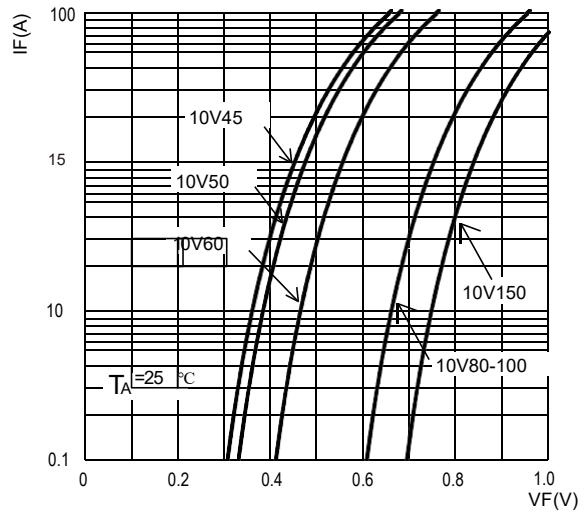


Fig3: Surge Forward Current Capability

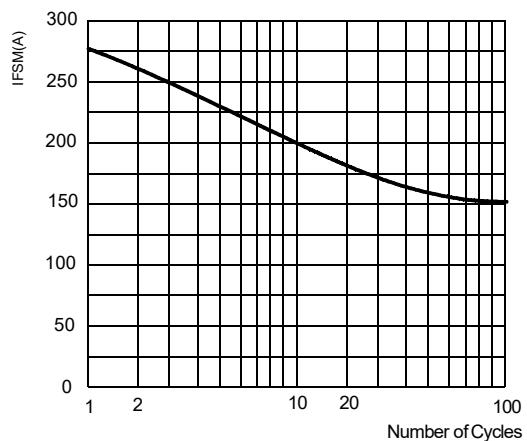


Fig4: Typical Reverse Characteristics

